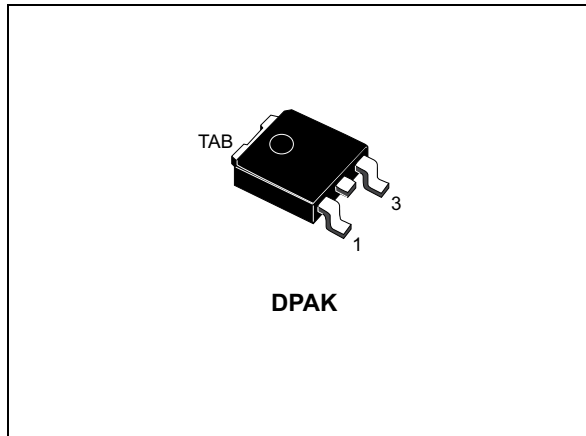


Automotive-grade N-channel 500 V, 0.28 Ω typ., 12 A MDmesh™ II Power MOSFET in a DPAK package

Datasheet - production data



Features

| Order code | V_{DS} @ T_{Jmax} | $R_{DS(on)}$ max | I_D |
|------------|-----------------------|------------------|-------|
| STD14NM50N | 550 V | 0.32 Ω | 12 A |

- Designed for automotive applications and AEC-Q101 qualified
- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using the second generation of MDmesh™ technology. This revolutionary Power MOSFET associates a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. It is therefore suitable for the most demanding high efficiency converters.

Figure 1. Internal schematic diagram

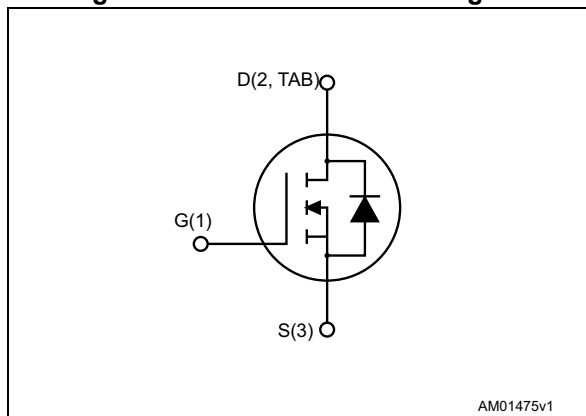


Table 1. Device summary

| Order code | Marking | Package | Packaging |
|------------|---------|---------|---------------|
| STD14NM50N | 14NM50N | DPAK | Tape and reel |

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1 Electrical ratings

Table 2. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|-------------|------------------|
| V_{DS} | Drain-source voltage | 500 | V |
| V_{GS} | Gate-source voltage | ± 25 | V |
| I_D | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 12 | A |
| I_D | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 8 | A |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 48 | A |
| P_{TOT} | Total dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 90 | W |
| $dv/dt^{(2)}$ | Peak diode recovery voltage slope | 15 | V/ns |
| T_{stg} | Storage temperature | - 55 to 150 | $^\circ\text{C}$ |
| T_j | Max. operating junction temperature | 150 | $^\circ\text{C}$ |

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 12\text{ A}$, $di/dt \leq 400\text{ A/s}$, $V_{DS\text{ peak}} \leq V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$.

Table 3. Thermal data

| Symbol | Parameter | Value | Unit |
|---------------------|--------------------------------------|-------|--------------------|
| $R_{thj-case}$ | Thermal resistance junction-case max | 1.39 | $^\circ\text{C/W}$ |
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb max | 50 | $^\circ\text{C/W}$ |

1. When mounted on 1inch² FR-4 board, 2 oz Cu.

Table 4. Avalanche data

| Symbol | Parameter | Value | Unit |
|----------|--|-------|------|
| I_{AR} | Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max) | 4 | A |
| E_{AS} | Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | 172 | mJ |

2 Electrical characteristics

($T_C = 25\text{ °C}$ unless otherwise specified).

Table 5. On /off states

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|-----------------------------------|--|------|------|-----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage | $V_{GS} = 0, I_D = 1\text{ mA}$ | 500 | | | V |
| I_{DSS} | Zero gate voltage drain current | $V_{GS} = 0, V_{DS} = 500\text{ V}$ | | | 1 | μA |
| | | $V_{GS} = 0, V_{DS} = 500\text{ V}, T_C = 125\text{ °C}$ | | | 100 | μA |
| I_{GSS} | Gate-body leakage current | $V_{DS} = 0, V_{GS} = \pm 25\text{ V}$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on-resistance | $V_{GS} = 10\text{ V}, I_D = 6\text{ A}$ | | 0.28 | 0.32 | Ω |

Table 6. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------------------|-------------------------------|---|------|------|------|----------|
| C_{iss} | Input capacitance | $V_{GS} = 0, V_{DS} = 50\text{ V}, f = 1\text{ MHz}$ | - | 816 | - | pF |
| C_{oss} | Output capacitance | | - | 60 | - | pF |
| C_{rss} | Reverse transfer capacitance | | - | 3 | - | pF |
| $C_{oss\text{ eq.}}^{(1)}$ | Equivalent output capacitance | $V_{GS} = 0, V_{DS} = 0\text{ to }50\text{ V}$ | - | 157 | - | pF |
| R_G | Intrinsic gate resistance | $f = 1\text{ MHz open drain}$ | - | 4.5 | - | Ω |
| Q_g | Total gate charge | $V_{DD} = 400\text{ V}, I_D = 12\text{ A}, V_{GS} = 10\text{ V}$ (see Figure 13) | - | 27 | - | nC |
| Q_{gs} | Gate-source charge | | - | 5 | - | nC |
| Q_{gd} | Gate-drain charge | | - | 15 | - | nC |

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}

Table 7. Switching times

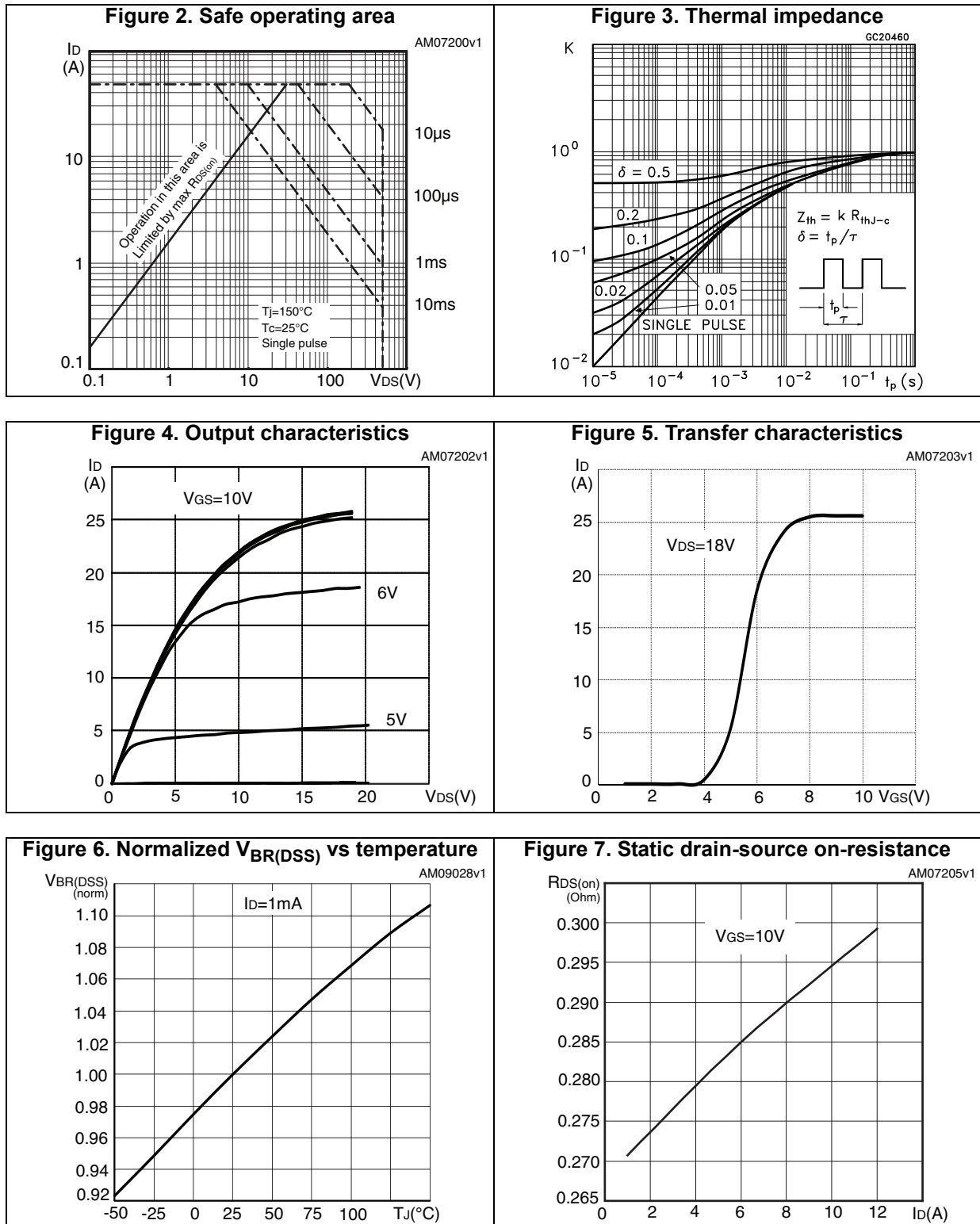
| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|--------------|---------------------|---|------|------|------|------|
| $t_{d(on)}$ | Turn-on delay time | $V_{DD} = 400\text{ V}$, $I_D = 12\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 10\text{ V}$ (see Figure 13) | - | 12 | - | ns |
| t_r | Rise time | | - | 16 | - | ns |
| $t_{d(off)}$ | Turn-off-delay time | | - | 42 | - | ns |
| t_f | Fall time | | - | 22 | - | ns |

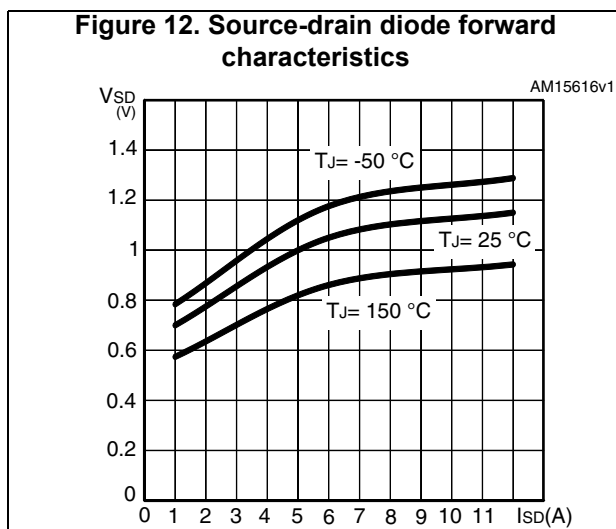
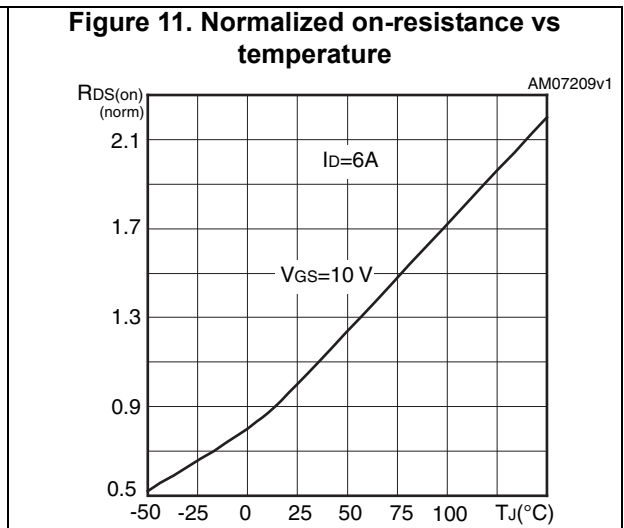
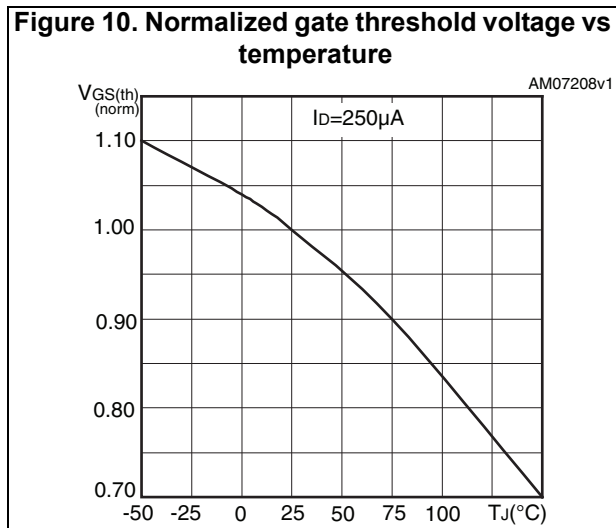
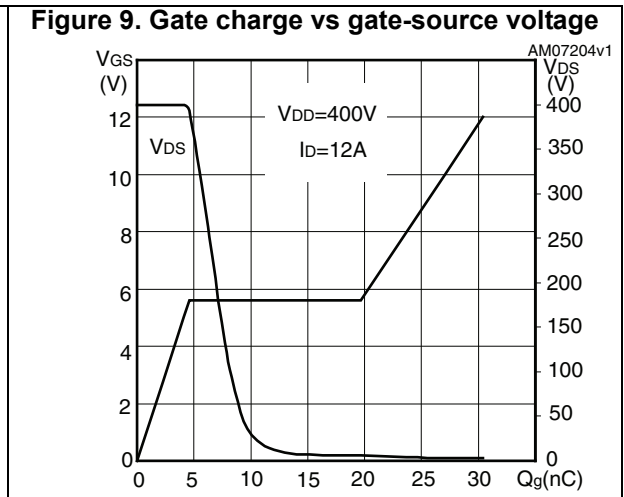
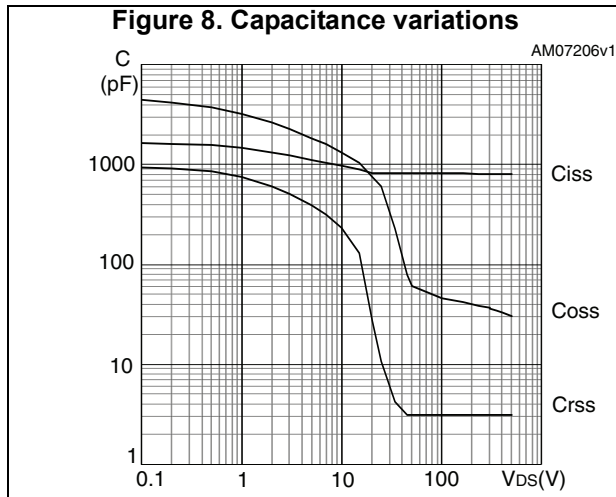
Table 8. Source drain diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------|---|------|------|------|---------------|
| I_{SD} | Source-drain current | | - | | 12 | A |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | - | | 48 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $V_{GS} = 0$, $I_{SD} = 12\text{ A}$ | - | | 1.6 | V |
| t_{rr} | Reverse recovery time | $I_{SD} = 12\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 17) | - | 252 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 2.8 | | μC |
| I_{RRM} | Reverse recovery current | | - | 22 | | A |
| t_{rr} | Reverse recovery time | $I_{SD} = 12\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see Figure 17) | - | 300 | | ns |
| Q_{rr} | Reverse recovery charge | | - | 3.3 | | μC |
| I_{RRM} | Reverse recovery current | | - | 22.2 | | A |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)





3 Test circuits

Figure 13. Switching times test circuit for resistive load

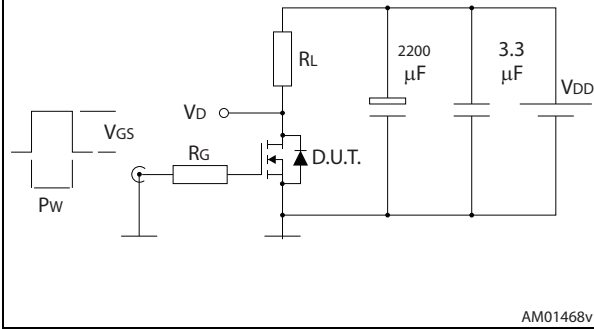


Figure 14. Gate charge test circuit

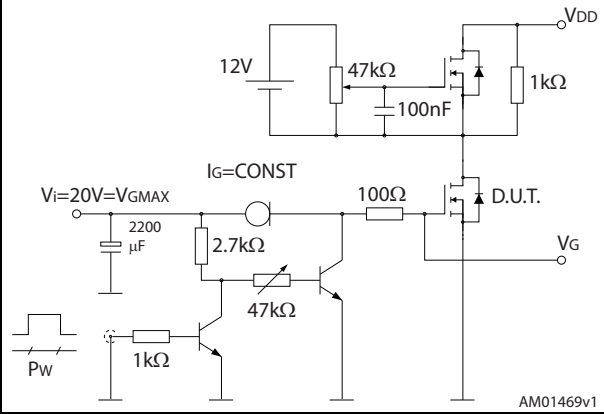


Figure 15. Test circuit for inductive load switching and diode recovery times

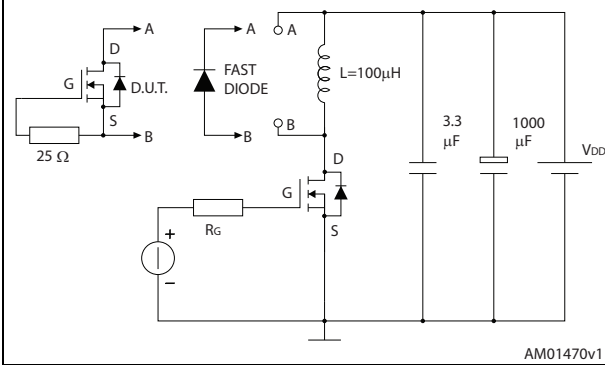


Figure 16. Unclamped inductive load test circuit

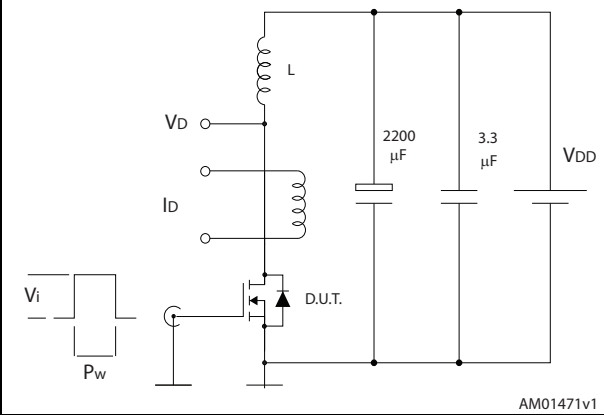


Figure 17. Unclamped inductive waveform

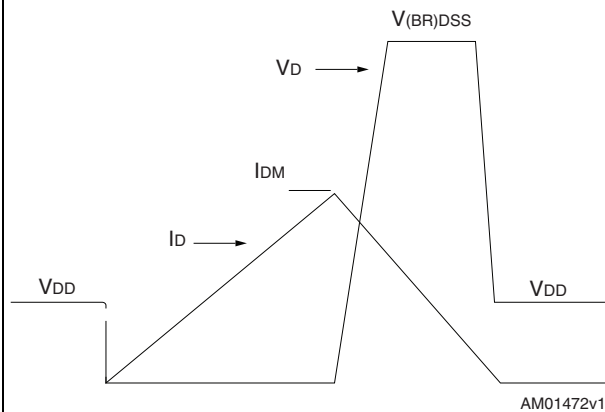
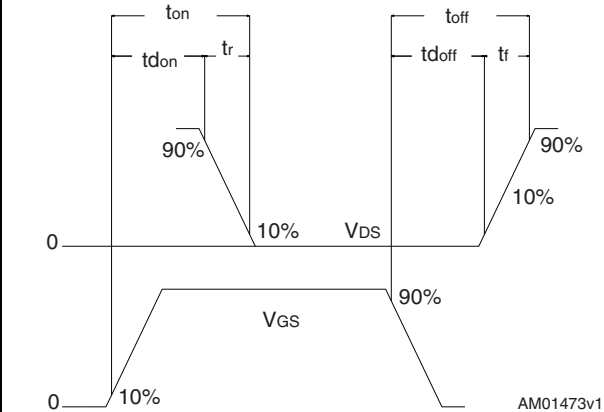


Figure 18. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

4.1 DPAK package information

Figure 19. DPAK (TO-252) type A2 package outline

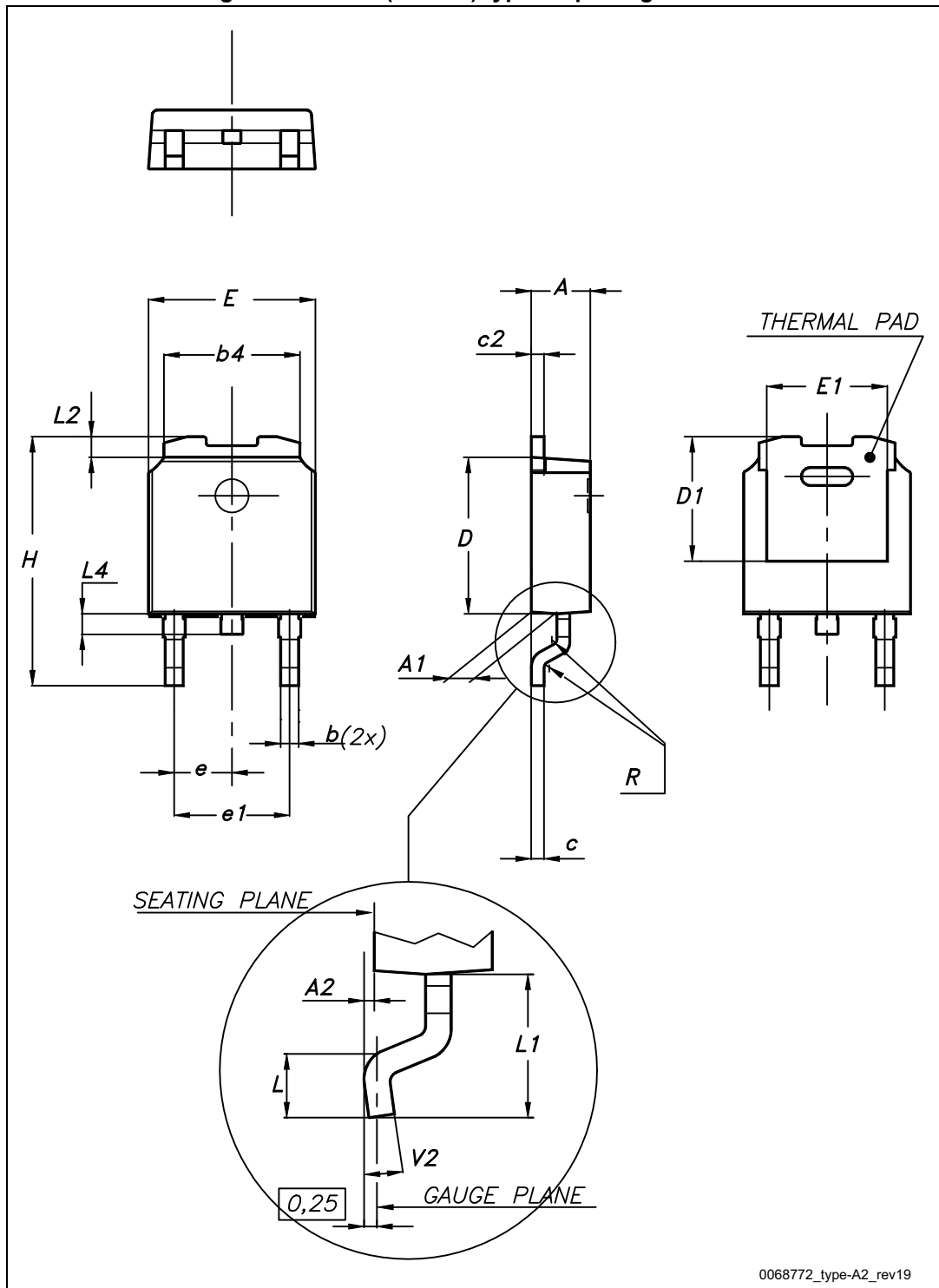
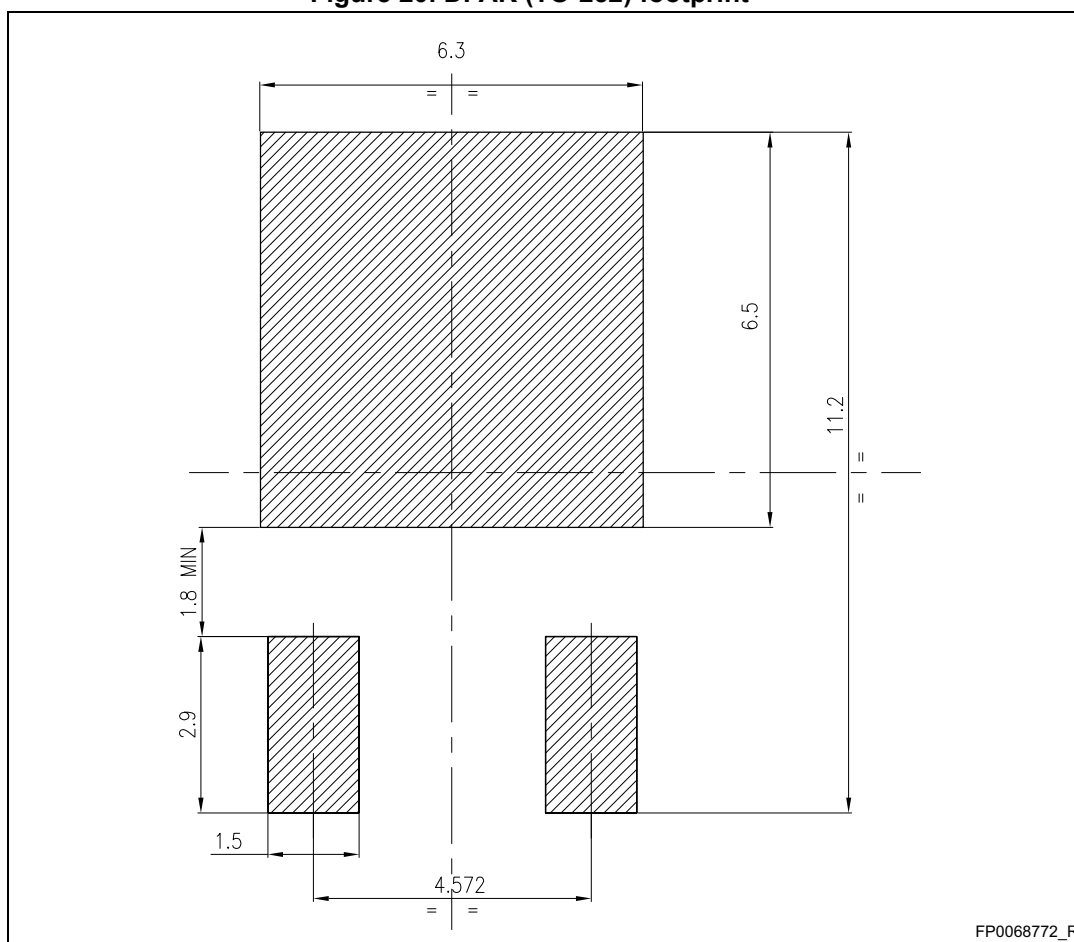


Table 9. DPAK (TO-252) type A2 mechanical data

| Dim. | mm | | |
|------|------|------|-------|
| | Min. | Typ. | Max. |
| A | 2.20 | | 2.40 |
| A1 | 0.90 | | 1.10 |
| A2 | 0.03 | | 0.23 |
| b | 0.64 | | 0.90 |
| b4 | 5.20 | | 5.40 |
| c | 0.45 | | 0.60 |
| c2 | 0.48 | | 0.60 |
| D | 6.00 | | 6.20 |
| D1 | 4.95 | 5.10 | 5.25 |
| E | 6.40 | | 6.60 |
| E1 | 5.10 | 5.20 | 5.30 |
| e | 2.16 | 2.28 | 2.40 |
| e1 | 4.40 | | 4.60 |
| H | 9.35 | | 10.10 |
| L | 1.00 | | 1.50 |
| L1 | 2.60 | 2.80 | 3.00 |
| L2 | 0.65 | 0.80 | 0.95 |
| L4 | 0.60 | | 1.00 |
| R | | 0.20 | |
| V2 | 0° | | 8° |

Figure 20. DPAK (TO-252) footprint (a)



a. All dimensions are in millimeters

5 Packing mechanical data

Figure 21. Tape

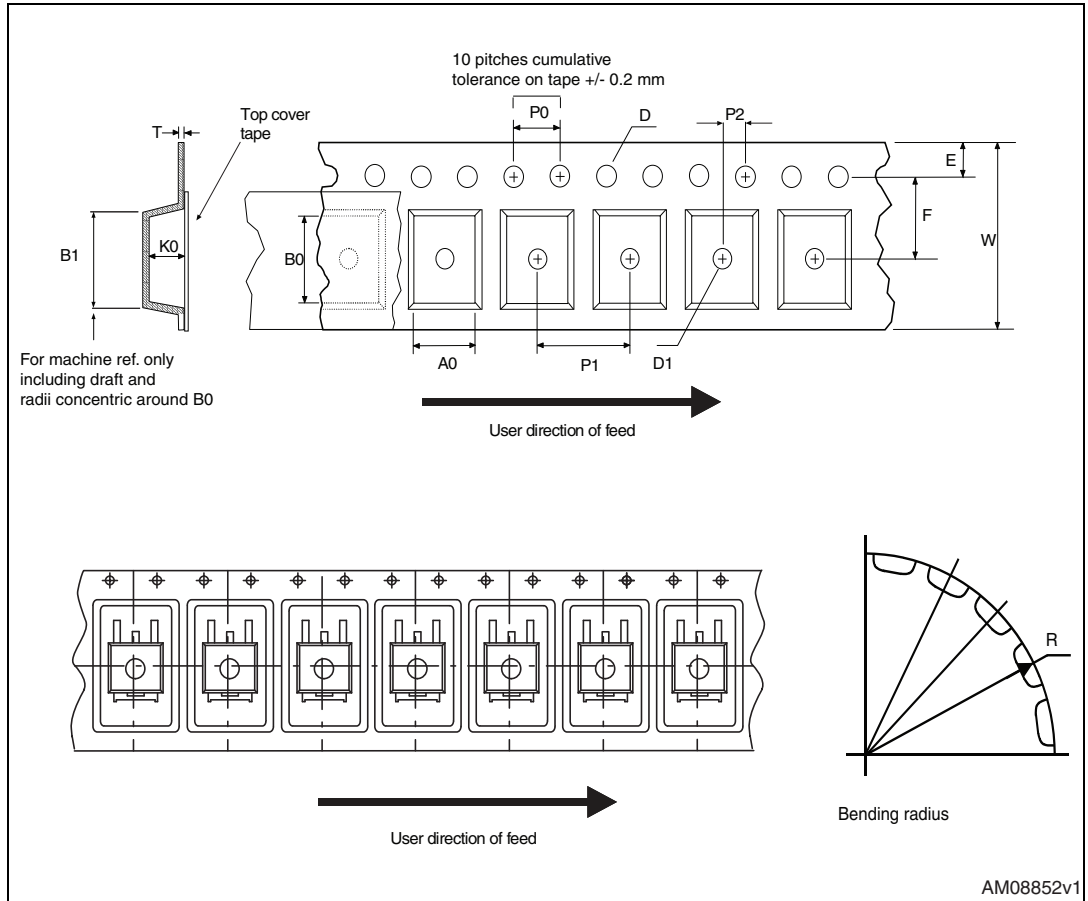


Figure 22. Reel

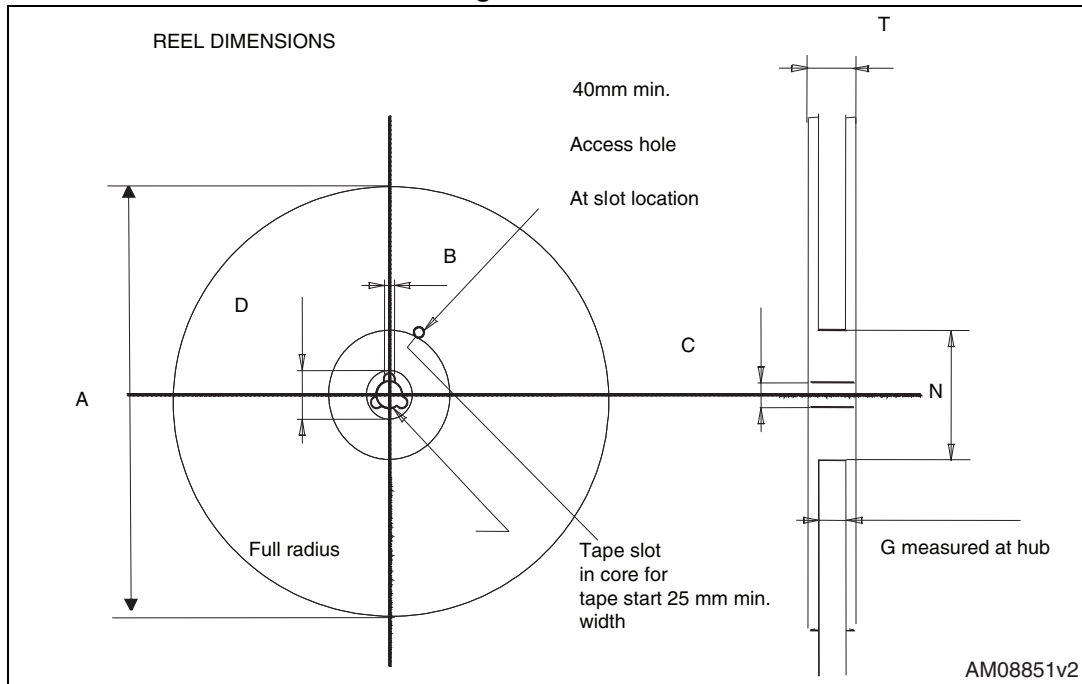


Table 10. D²PAK (TO-263) tape and reel mechanical data

| Tape | | | Reel | | |
|------|------|------|----------|------|------|
| Dim. | mm | | Dim. | mm | |
| | Min. | Max. | | Min. | Max. |
| A0 | 10.5 | 10.7 | A | | 330 |
| B0 | 15.7 | 15.9 | B | 1.5 | |
| D | 1.5 | 1.6 | C | 12.8 | 13.2 |
| D1 | 1.59 | 1.61 | D | 20.2 | |
| E | 1.65 | 1.85 | G | 24.4 | 26.4 |
| F | 11.4 | 11.6 | N | 100 | |
| K0 | 4.8 | 5.0 | T | | 30.4 |
| P0 | 3.9 | 4.1 | | | |
| P1 | 11.9 | 12.1 | Base qty | | 1000 |
| P2 | 1.9 | 2.1 | Bulk qty | | 1000 |
| R | 50 | | | | |
| T | 0.25 | 0.35 | | | |
| W | 23.7 | 24.3 | | | |

6 Revision history

Table 11. Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 27-Jun-2014 | 1 | First release. |
| 03-Sep-2015 | 2 | Updated <i>DPAK package information</i> . Minor text changes. |
| 09-Sep-2015 | 3 | Updated figure and table MD for DPAK package information Minor text changes. |

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